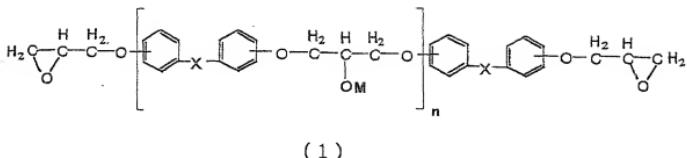
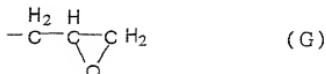


is represented by Formula (1):



(1)

(In the formula, X is -CH₂- or -C(CH₃)₂-, n is an integer of 1 or more, and M is hydrogen or a group represented by Formula (G) as shown below:



(G)

, provided that M is a group represented by Formula (G) if n is 1, while at least one M is a group represented by Formula (G) and each the remainders being hydrogen if n is an integer more than 1).

(7) A resin composition comprising an urethane oligomer(A) according to any of Claim (1) to (4) and a thermoplastic polymer(D).

(8) A resin composition according to Claim (5) or (6), comprising a diluent(C).

(9) A resin composition according to Claim (7) or (8), wherein said diluent(C) is a reactive diluent(C-1).

- (10) A resin composition according to any of Claim (5) to (9) comprising a photopolymerization initiator(E).
- (11) A resin composition comprising an urethane oligomer(A) according to any of Claim (1) to (4), a thermoplastic polymer(D) and a photopolymerization initiator(E).
- (12) A resin composition according to Claim (11), wherein said thermoplastic polymer (D) is a polymer having carboxyl groups.
- (13) A resin composition according to any of Claim (1) to (10) comprising a thermosetting component(F).
- (14) A resin composition according to any of Claim (5) to (13), wherein said resin composition is prepared for the solder resist in a printed circuit board or for an interlayer dielectric layer.
- (15) A photosensitive film comprising being prepared by laminating the layer of a resin composition according to any of Claim (10) to (14) on a supporting film.
- (16) A photosensitive film according to Claim (15), wherein said photosensitive film is prepared for a printed circuit board.
- (17) A cured product of the resin composition according to any of Claim (5) to (16).
- (18) An article comprising having the layer of a cured product according to Claim (17).
- (19) An article according to Claim (18), wherein said article is a printed circuit board.
- (20) A two-liquid type of resin composition set comprising a

principal resin composition which contains (1)an urethane oligomer(A)or the salt thereof, (2)either an unsaturated group-containing polycarboxylic acid resin(B) or a thermoplastic polymer(D), and (3) a photopolymerization initiator(E)and a curing agent composition which contains a thermosetting component(F).

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